

**AMENDMENTS TO THE SPECIFICATION:**

*Please amend the paragraph on page 16, beginning at line 5 as follows:*

A photoresist film [[422]]42 is then formed on the passivation layer 40 such that the passivation layer 40 is exposed at regions where bonding electrodes are to be formed, respectively, as shown in Fig. 3e. The ~~boding~~ bonding electrode forming regions correspond to regions where desired portions of the transparent electrode 38 and first conductivity type clad layer 33 are positioned. These regions are arranged so that they are spaced apart from each other by a sufficient distance while being symmetrically arranged.

**Abstract:**

Please replace the current Abstract with the following replacement/new Abstract